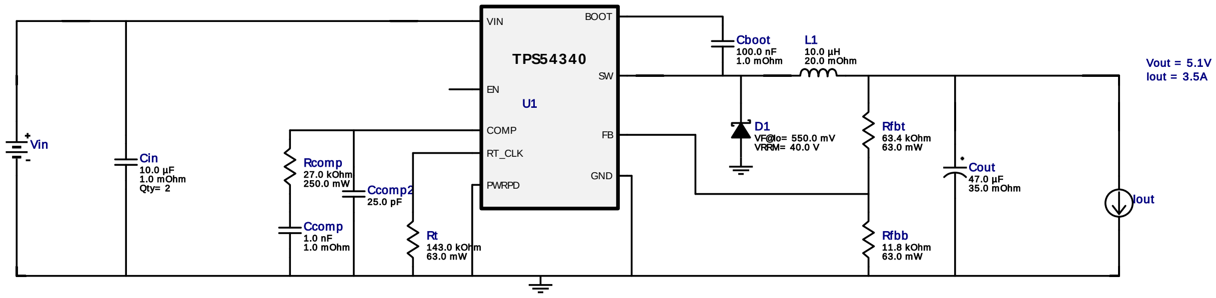
Texas Instruments

WEBENCH ® Design Report

VinMin = 6.0V
VinMax = 30.0V
Vout = 5.1V
Iout = 3.5A

Device = TPS54340DDAR
Topology = Buck
Created = 2019-08-10 23:13:14.912
BOM Cost = $3.75
BOM Count = 13
Total Pd = 2.4W

Design : 10 TPS54340DDAR
TPS54340DDAR 6V-30V to 5.10V @ 3.5A

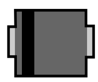
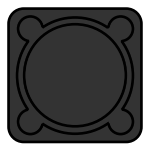


Design Alerts

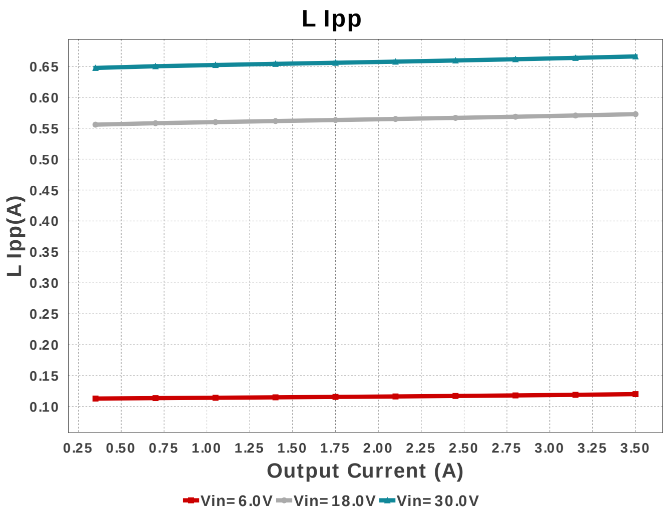
Component Selection Information

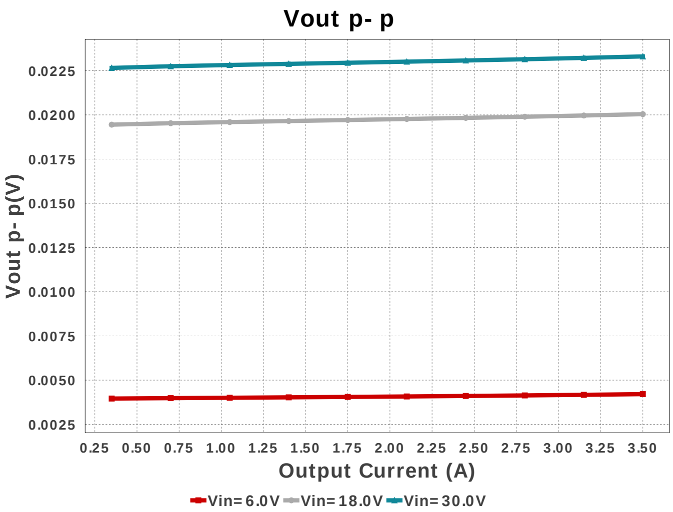
TI does not recommend using TPS54340 part in a new design. Please use TPS54340B which is an EXACT EQUIVALENT in functionality and parametrics to the compared device.

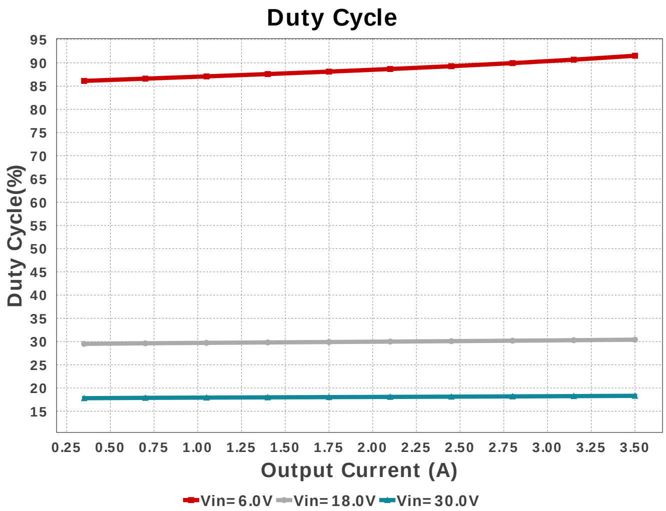
Electrical BOM

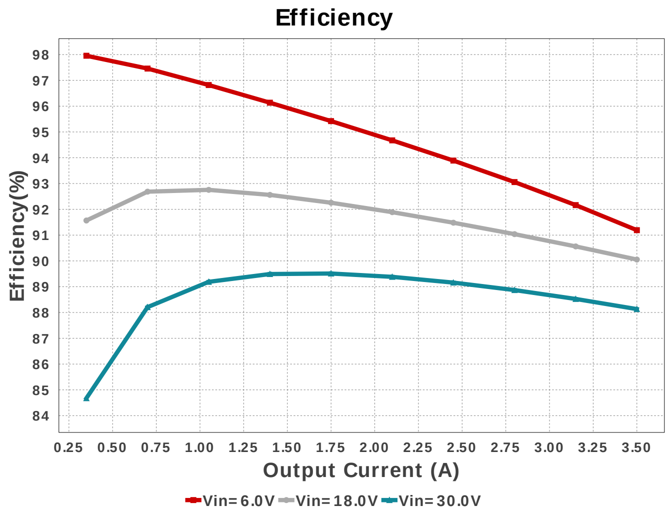
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cboot	Yageo	CC0805KRX7R7BB104 Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	$0.02	0805 7 mm²
Ccomp	MuRata	GRM1885C1H102JA01D Series= C0G/NP0	Cap= 1.0 nF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 0.0 A	1	$0.02	0603 5 mm²
Ccomp2	Samsung Electro-Mechanics	CL10C250JB8NNNC Series= C0G/NP0	Cap= 25.0 pF VDC= 50.0 V IRMS= 0.0 A	1	$0.01	0603 5 mm²
Cin	MuRata	GRM32ER71H106KA12L Series= X7R	Cap= 10.0 uF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 6.0 A	2	$0.43	 1210_270 15 mm²
Cout	Panasonic	10TPE47MAZB Series= TPE	Cap= 47.0 uF ESR= 35.0 mOhm VDC= 10.0 V IRMS= 1.4 A	1	$0.38	 3528-21 17 mm²
D1	Diodes Inc.	B540C-13-F	VF@Io= 550.0 mV VRRM= 40.0 V	1	$0.17	 SMC 83 mm²
L1	Bourns	SRR1260-100M	L= 10.0 µH 20.0 mOhm	1	$0.50	 SRR1260 210 mm²
Rcomp	Yageo	RC1206FR-0727KL Series= ?	Res= 27.0 kOhm Power= 250.0 mW Tolerance= 1.0%	1	$0.01	 1206 11 mm²

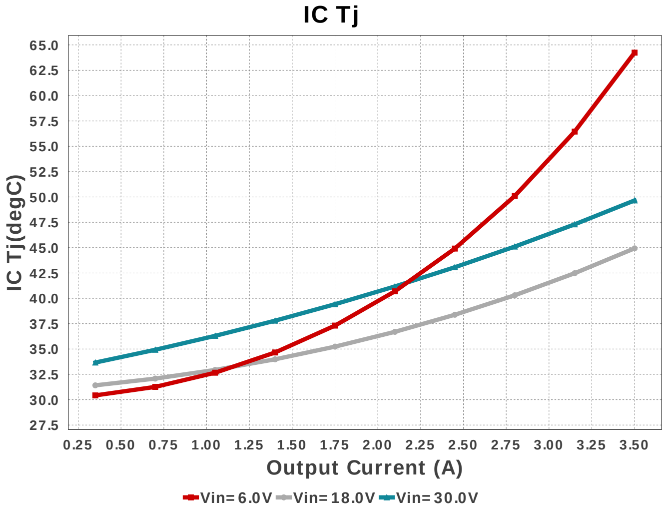
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rfbb	Vishay-Dale	CRCW040211K8FKED Series= CRCW..e3	Res= 11.8 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
Rfbt	Vishay-Dale	CRCW040263K4FKED Series= CRCW..e3	Res= 63.4 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
Rt	Vishay-Dale	CRCW0402143KFKED Series= CRCW..e3	Res= 143.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
U1	Texas Instruments	TPS54340DDAR	Switcher	1	$1.75	R-PDSO-G8 55 mm^2

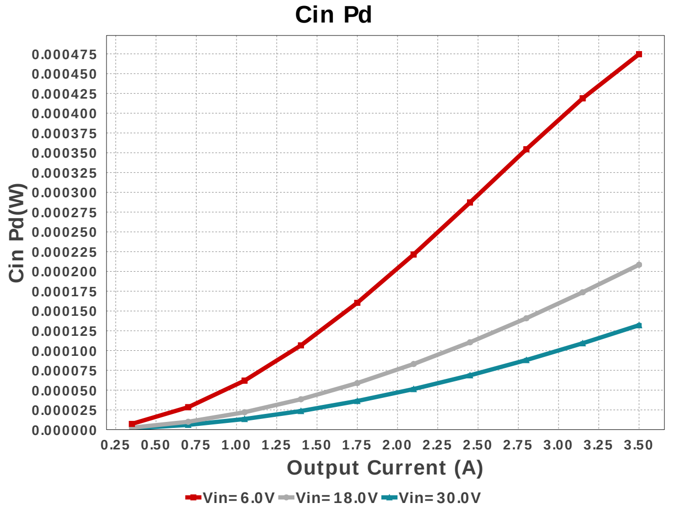


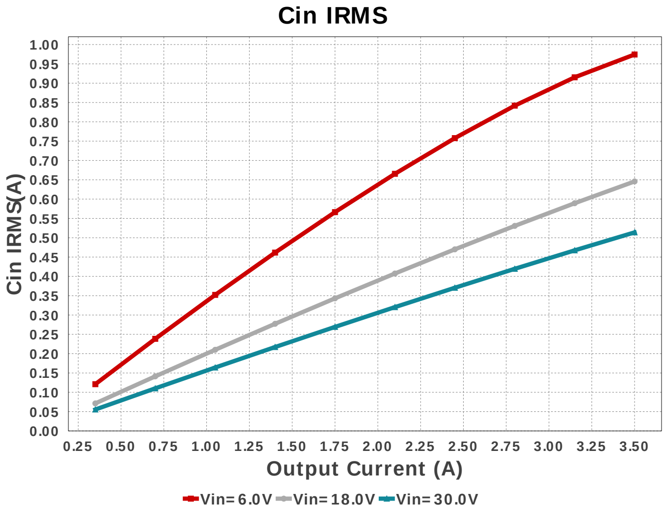


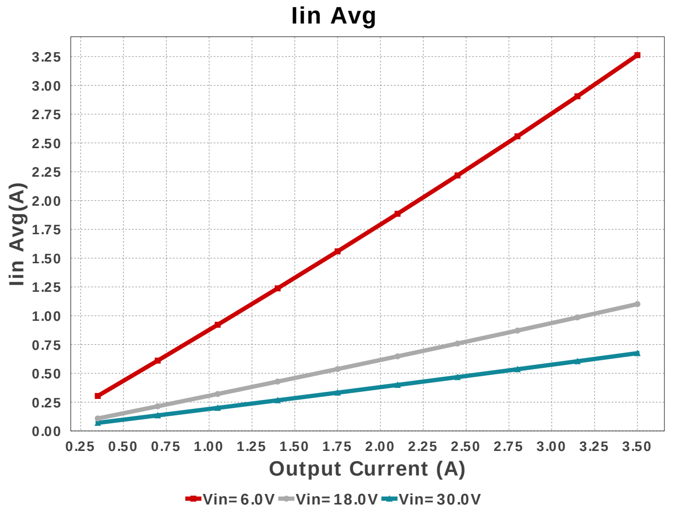


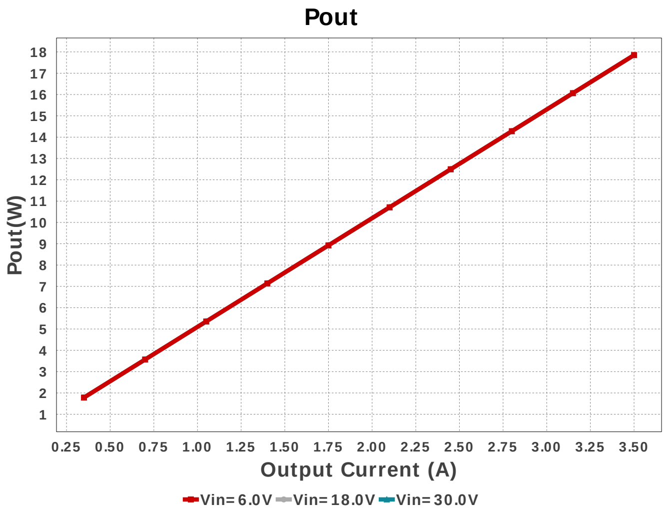


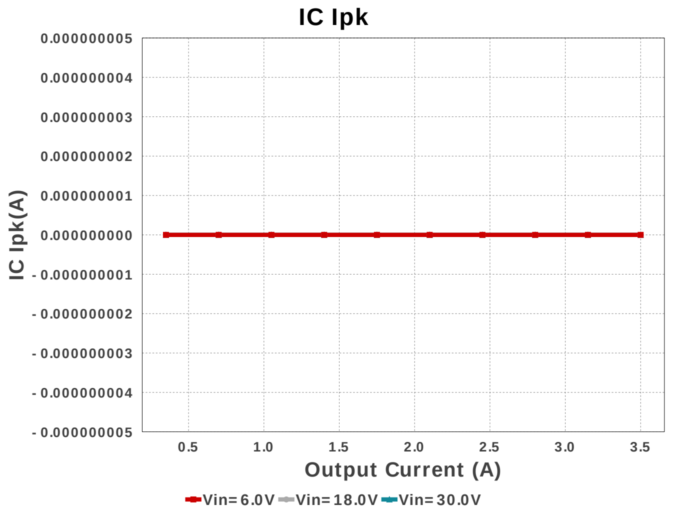

IC Tj
IC Tj(degC)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V

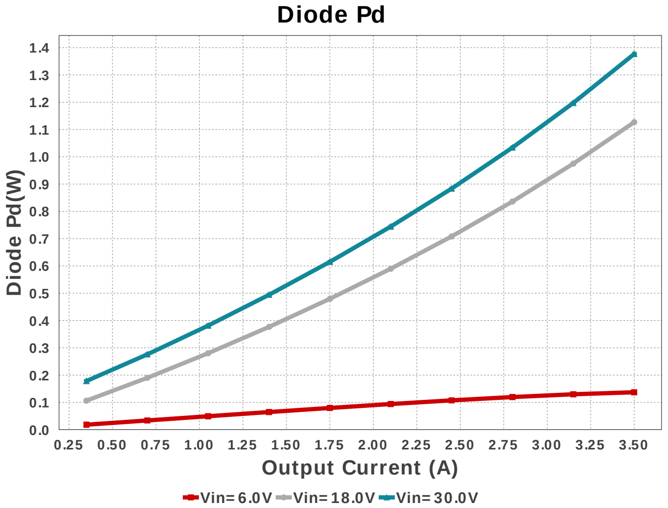

Cin Pd
Cin Pd(W)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V

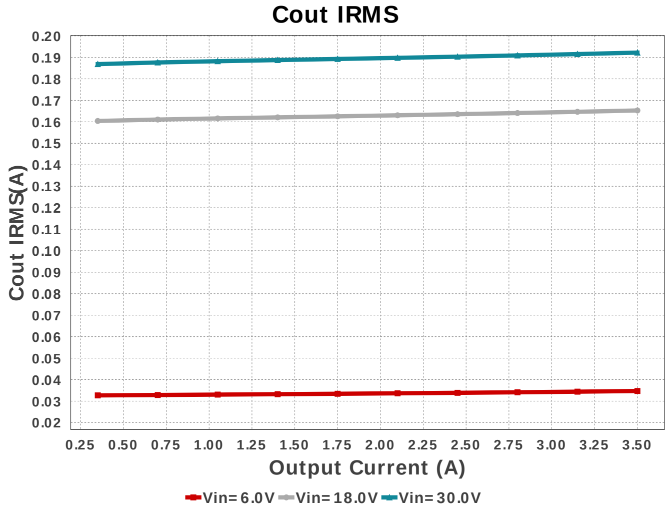

Cin IRMS
Cin IRMS(A)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V

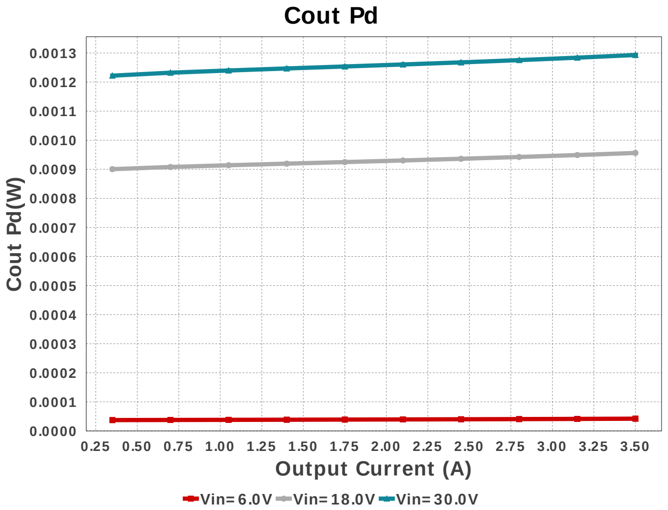

Iin Avg
Iin Avg(A)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V

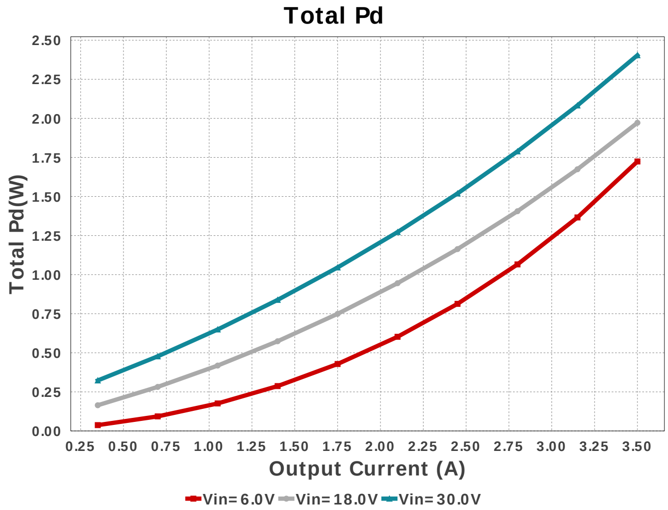

Pout
Pout(W)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V

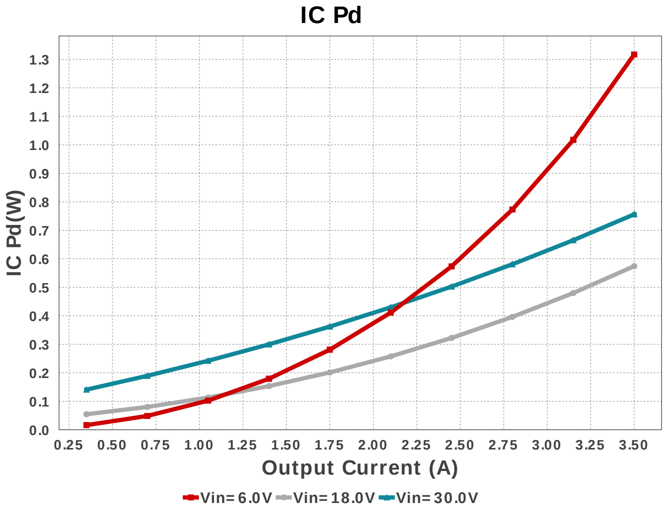

IC Ipk
IC Ipk(A)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V

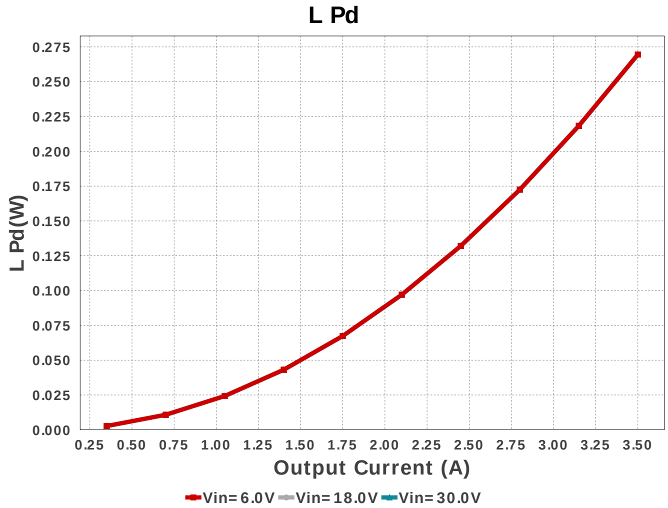

Diode Pd
Diode Pd(W)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V

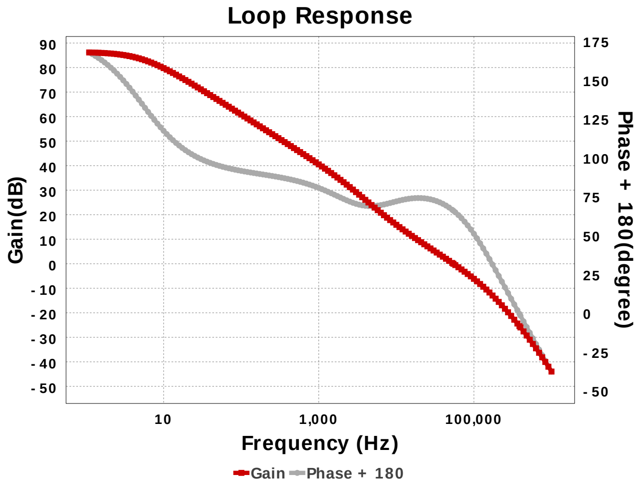

Cout IRMS
Cout IRMS(A)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V


Cout Pd
Cout Pd(W)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V


Total Pd
Total Pd(W)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V


IC Pd
IC Pd(W)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V


L Pd
L Pd(W)
Output Current (A)
Vin=6.0V Vin=18.0V Vin=30.0V



Operating Values

#	Name	Value	Category	Description
1.	BOM Count	13		Total Design BOM count
2.	Total BOM	$3.75		Total BOM Cost
3.	Cin IRMS	513.885 mA	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	132.04 µW	Capacitor	Input capacitor power dissipation
5.	Cout IRMS	192.213 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	1.293 mW	Capacitor	Output capacitor power dissipation
7.	Diode Pd	1.377 W	Diode	Diode power dissipation
8.	IC Ipk	0.0 A	IC	Peak switch current in IC
9.	IC Pd	756.08 mW	IC	IC power dissipation
10.	IC Tj	49.658 degC	IC	IC junction temperature
11.	ICThetaJA Effective	26.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
12.	Iin Avg	675.12 mA	IC	Average input current
13.	L Ipp	665.846 mA	Inductor	Peak-to-peak inductor ripple current
14.	L Pd	269.5 mW	Inductor	Inductor power dissipation
15.	Cin Pd	132.04 µW	Power	Input capacitor power dissipation
16.	Cout Pd	1.293 mW	Power	Output capacitor power dissipation
17.	Diode Pd	1.377 W	Power	Diode power dissipation
18.	IC Pd	756.08 mW	Power	IC power dissipation
19.	L Pd	269.5 mW	Power	Inductor power dissipation
20.	Total Pd	2.404 W	Power	Total Power Dissipation
21.	Cross Freq	54.389 kHz	System Information	Bode plot crossover frequency
22.	Duty Cycle	18.318 %	System Information	Duty cycle
23.	Efficiency	88.132 %	System Information	Steady state efficiency
24.	FootPrint	431.0 mm^2	System Information	Total Foot Print Area of BOM components
25.	Frequency	685.024 kHz	System Information	Switching frequency
26.	Gain Marg	-25.448 dB	System Information	Bode Plot Gain Margin
27.	Iout	3.5 A	System Information	Iout operating point
28.	Low Freq Gain	86.162 dB	System Information	Gain at 1Hz
29.	Mode	CCM	System Information	Conduction Mode
30.	Phase Marg	66.408 deg	System Information	Bode Plot Phase Margin
31.	Pout	17.85 W	System Information	Total output power
32.	Vin	30.0 V	System Information	Vin operating point
33.	Vout	5.1 V	System Information	Operational Output Voltage
34.	Vout Actual	5.098 V	System Information	Vout Actual calculated based on selected voltage divider resistors
35.	Vout Tolerance	2.72 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
36.	Vout p-p	23.305 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	3.5	Maximum Output Current
VinMax	30.0	Maximum input voltage
VinMin	6.0	Minimum input voltage
Vout	5.1	Output Voltage
base_pn	TPS54340	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

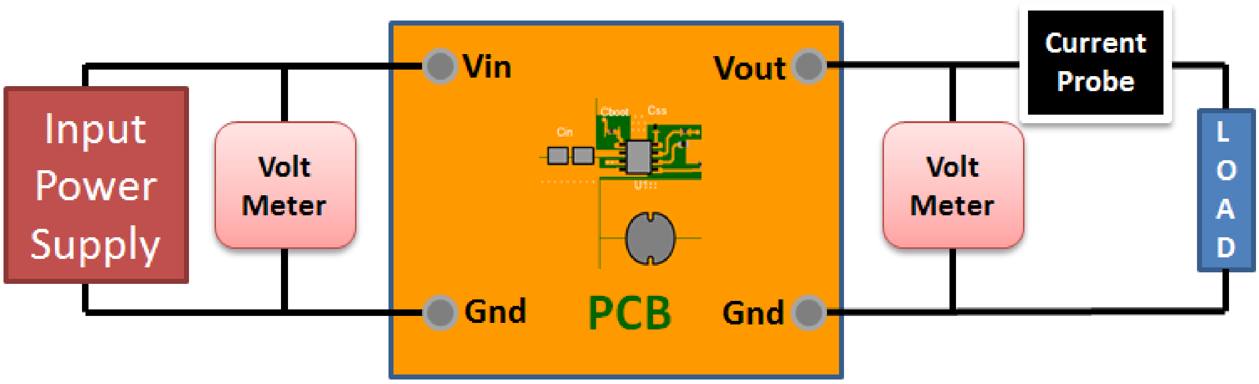
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 6.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. TI does not recommend using TPS54340 part in a new design. Please use TPS54340B which is an EXACT EQUIVALENT in functionality and parametrics to the compared device.

2. Master key : 305710B8CC4DC84B[v1]

3. **TPS54340** Product Folder : http://www.ti.com/product/TPS54340 : contains the data sheet and other resources.